



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D *: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-11-26
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	MYYG*UP79J51	A	SA1A	2013-11-26
Amount	UoM	Unit type	ST ECOPACK Grade	
24.40	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	3X3X0.95	11	No lead	
Comment	VFDFPN 6 3X3 0,95 PITCH; MD valid for CP :ST1L05APU33R.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-20th June 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	MYYG*UP79J51					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	0.442	mg	Supplier	Silicon Die	Silicon (Si)	7440-21-3		0.416	mg	941176	17049
die (s)			mg	Supplier	metallization	Aluminium (Al)	7429-90-5		0.005	mg	11312	205
die (s)			mg	Supplier	metallization	Titanium Nitride (TiN)	25583-20-4		0.003	mg	6787	123
die (s)			mg	Supplier	metallization	Tungsten (W)	7440-33-7		0.004	mg	9050	164
die (s)			mg	Supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.001	mg	2262	41
die (s)			mg	Supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.009	mg	20362	369
die (s)			mg	Supplier	passivation	Gamma-butyrolactone	96-48-0		0.003	mg	6787	123
die (s)			mg	Supplier	passivation	Polyhydroxyamide	55295-98-2		0.001	mg	2262	41
Leadframe	Copper and its alloy	9.021	mg	Supplier	Alloy	Copper (Remaining)	7440-50-8		8.714	mg	965968	357131
Leadframe			mg	Supplier	Alloy	Iron (2.1~2.6%)	7439-89-6		0.204	mg	22614	8361
Leadframe			mg	Supplier	Alloy	Phosphorus (0.015~0.15%)	7723-14-0		0.002	mg	222	82
Leadframe			mg	Supplier	Alloy	Zinc (0.05~0.20%)	7440-66-6		0.011	mg	1219	451
Leadframe			mg	Supplier	Alloy	Silver (0.5~1.5%)	7440-22-4		0.09	mg	9977	3689
Die Attach	Other Organic Material	0.14	mg	Supplier	Glue	Silver (80 - 100%)	7440-22-4		0.113	mg	807143	4631
Die Attach			mg	Supplier	Glue	Carbocyclic Acrylates (10 -30%)	proprietary		0.014	mg	100000	574
Die Attach			mg	Supplier	Glue	Bismaleimide resin (1-10%)	proprietary		0.004	mg	28571	164
Die Attach			mg	Supplier	Glue	2-preponic acid, 2-methyl (1-10%)	68586-19-6		0.004	mg	28571	164
Die Attach			mg	Supplier	Glue	Additive (1-10%)	proprietary		0.004	mg	28571	164
Die Attach			mg	Supplier	Glue	Dicumyl peroxide (0.1 - 1.0)	80-43-3		0.001	mg	7143	41
Bonding Wire	Other Inorganic Material	0.19	mg	Supplier	Bonding Wire	Au	7440-57-5		0.19	mg	1000000	7787
Encapsulation	Other Organic Material	13.988	mg	Supplier	Molding Compound	Fused Silica (75-95)	60676-86-0		13.106	mg	936946	537131
Encapsulation			mg	Supplier	Molding Compound	Epoxy resin (1-5)	proprietary		0.42	mg	30026	17213
Encapsulation			mg	Supplier	Molding Compound	Phenol resin (1-5)	proprietary		0.42	mg	30026	17213
Encapsulation			mg	Supplier	Molding Compound	Carbon Black (0.1-0.5)	proprietary		0.042	mg	3003	1721
Finishing	Other Inorganic Material	0.619	mg	Supplier	Connection coating	Sn	7440-31-5		0.619	mg	1000000	25369